

E1UGB30-50.000M



ITEM DESCRIPTION

Quartz Crystal Resonator HC49/US Short Thru-Hole 2.5mm Height Metal Resistance Weld Seal 50.000MHz $\pm 15\text{ppm}$ at 25°C, $\pm 30\text{ppm}$ over 0°C to +70°C 30pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

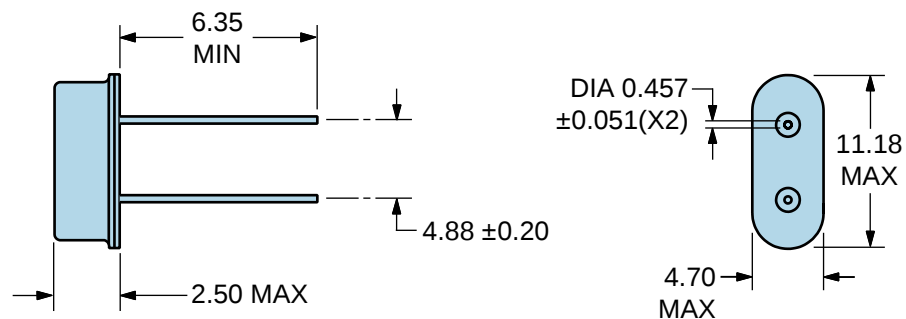
Nominal Frequency	50.000MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C, $\pm 30\text{ppm}$ over 0°C to +70°C
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Load Capacitance	30pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	100 Ohms Maximum
Mode of Operation	AT-Cut Third Overtone
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

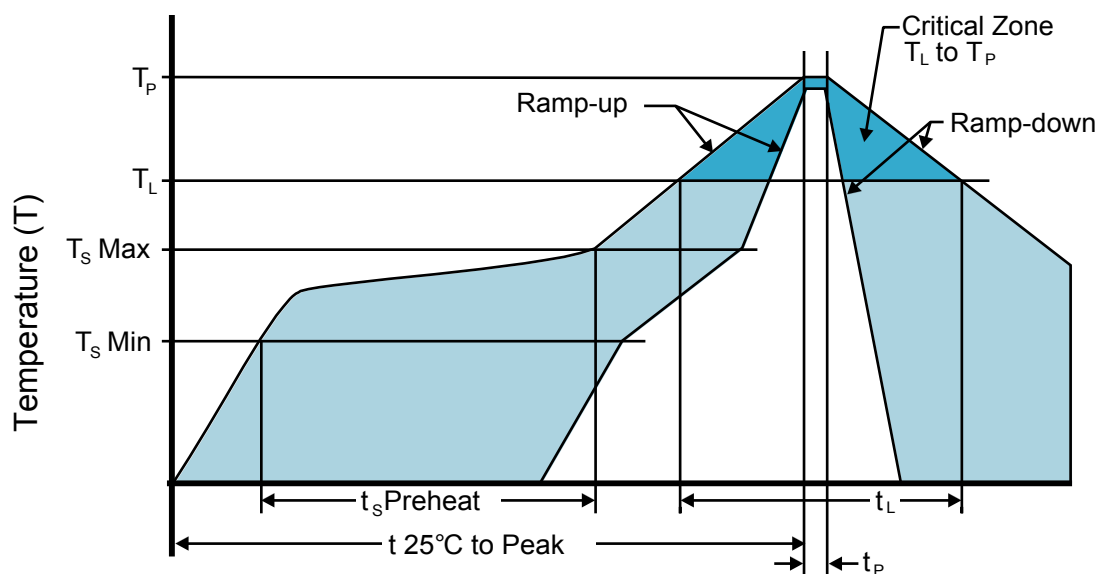
ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

E1UGB30-50.000M **MECHANICAL DIMENSIONS (all dimensions in millimeters)**

LINE	MARKING
1	E50.000M <i>E=EclipseTek Designator</i>



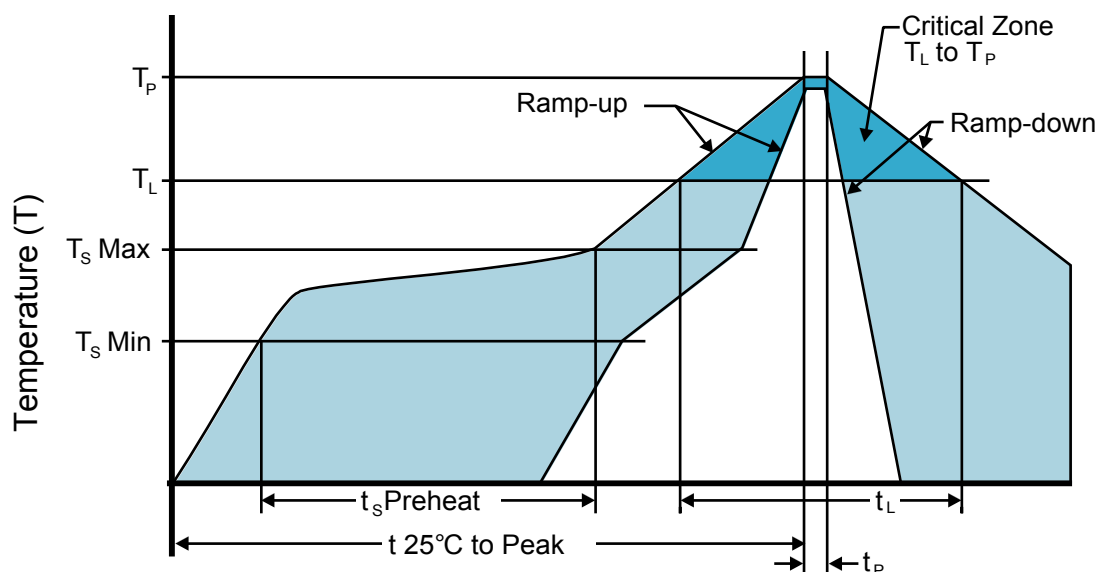
Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder) Time (t)

Ts MAX to Tl (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (Tl to Tp)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (Tl)	217°C
- Time (tl)	60 - 150 Seconds
Peak Temperature (Tp)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (Tp Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to back of PCB board and device leads only.

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder) Time (t)

Ts MAX to Tl (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (Tl to Tp)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (Tl)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (Tp)	245°C Maximum
Target Peak Temperature (Tp Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (tp)	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to back of PCB board and device leads only.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)